

Amendments To The Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

Claim 1. (Currently Amended) An electroconductive silicone pressure-sensitive adhesive composition, comprising:

(A) 100 parts by weight of an organopolysiloxane having the average compositional formula (1):



wherein R is independently a substituted or unsubstituted monovalent hydrocarbon radical having 1 to 10 carbon atoms, and "a" is a positive number of 1.95 to 2.05[[,]]; and

(B) 50 to 250 parts by weight of an organopolysiloxane comprising structural units of the general formula (2):



wherein R¹ is independently a hydroxyl radical or a substituted or unsubstituted monovalent hydrocarbon radical having 1 to 10 carbon atoms and SiO_{4/2} units, in a molar ratio (R¹₃SiO_{1/2})/(SiO_{4/2}) ~~between~~ ranging from 0.5 and 1.2[[,]]; and

(C) 3 to 300 parts by weight per 100 parts by weight of components (A) and (B) combined of an electroconductive powder ~~including~~ comprising core particles of an inorganic material or organic resin which are surface coated with a layer of a silicon-base polymer having reductive effect or a partially or entirely ceramic layer thereof, which is in turn surface coated with a metal by plating[[,]]; and

(D) an effective amount to cure component (A) of a crosslinking agent.

Claim 2. (Currently Amended) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein, in the electroconductive powder (C), the core particles are made of an inorganic material having a specific gravity of up to 3.5 and are coated on ~~the~~ their outermost ~~surface~~ surfaces with a noble metal.

Claim 3. (Currently Amended) The electroconductive silicone pressure-sensitive adhesive composition of claim 2, wherein the noble metal is selected from the group consisting of silver, gold, palladium and platinum.

Claim 4. (Currently Amended) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein the crosslinking agent (D) comprises an organohydrogenpolysiloxane containing at least two silicon atom-bonded hydrogen atoms in a molecule and a platinum group catalyst, or an organic peroxide.

Claim 5. (New) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein the core particles have an average particle size ranging from 0.1 to 500 μm .

Claim 6. (New) The electroconductive silicone pressure-sensitive adhesive composition of claim 5, wherein the core particles have an average particle size ranging from 1 to 100 μm .

Claim 7. (New) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein the surface coating of metal is a metal selected from the

group consisting of at least one of nickel, copper, silver, cobalt, tungsten, iron, zinc, gold and platinum or Ni-P.

Claim 8. (New) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein the surface coating of metal has a thickness ranging from 0.01 to 10.0 μm .

Claim 9. (New) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein the amount of resin organopolysiloxane component (B) that is combined with organopolysiloxane component (A) ranges from 50 to 250 parts by weight of (B) per 100 parts by weight of (A).

Claim 10. (New) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein the amount of resin conductive powder component (C) that is combined with organopolysiloxane components (A) and (B) ranges from 3 to 300 parts by weight of (C) per 100 parts by weight of (A) and (B).

Claim 11. (New) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein the organohydrogenpolysiloxane crosslinking agent has the formula:



wherein R^6 is independently a substituted or unsubstituted monovalent C_{1-10} hydrocarbon group, $0 \leq s < 3$, $0 < t < 3$ and $0 < s+t < 3$.

Claim 12. (New) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein R of formula (1) is alkyl, cycloalkyl, alkenyl, aryl or aralkyl.

Claim 13. (New) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein organopolysiloxane component (A) has a degree of polymerization of at least 100.

Claim 14. (New) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein the molar ratio of component (B) ranges from 0.65 to 0.95.

Claim 15. (New) The electroconductive silicone pressure-sensitive adhesive composition of claim 1, wherein the silicon-based polymer that has a reductive effect has the formula:



wherein each of R^2 and R^3 is hydrogen or a substituted or unsubstituted monovalent hydrocarbon group, X is defined as R^2 , an alkoxy radical, halogen, oxygen, or nitrogen, $0.1 \leq b \leq 2$, $0 \leq c \leq 1$ and $0 \leq d \leq 0.5$ and $1 \leq b+c+d \leq 2.5$ and e ranges from 4 to 100,000.